

iC-OD OLGA OD4C

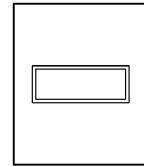
PACKAGE SPECIFICATION



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ORDERING INFORMATION

Type	Package	Options	Order Designation
iC-OD	OLGA OD4C	none	iC-OD OLGA OD4C

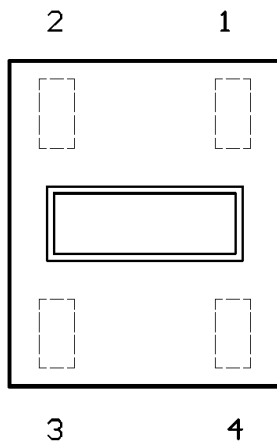


3.9 mm x 4.7 mm
RoHS compliant

PIN CONFIGURATION

PIN FUNCTIONS

(top view)



No. Name Function

1	GND	Ground
2	VCC	+4.5 to +13.2 V Supply Voltage
3	IAC1	Current Output 1
4	IAC2	Current Output 2

ABSOLUTE MAXIMUM RATINGS

Item No.	Symbol	Parameter	Conditions	Fig.	Min.	Typ.	Max.	Unit
TG1	Ta	Operating Ambient Temperature Range (extended temperature range on request)			-25		85	°C
TG2	Ts	Storage Temperature Range			-30		110	°C
TG3	Tpk	Reflow Soldering Peak Temperature	tpk < 20 s, convection reflow tpk < 20 s, vapour phase TOL (time on label) 8 h; please refer to Customer Information #7 for details				245 230	°C °C

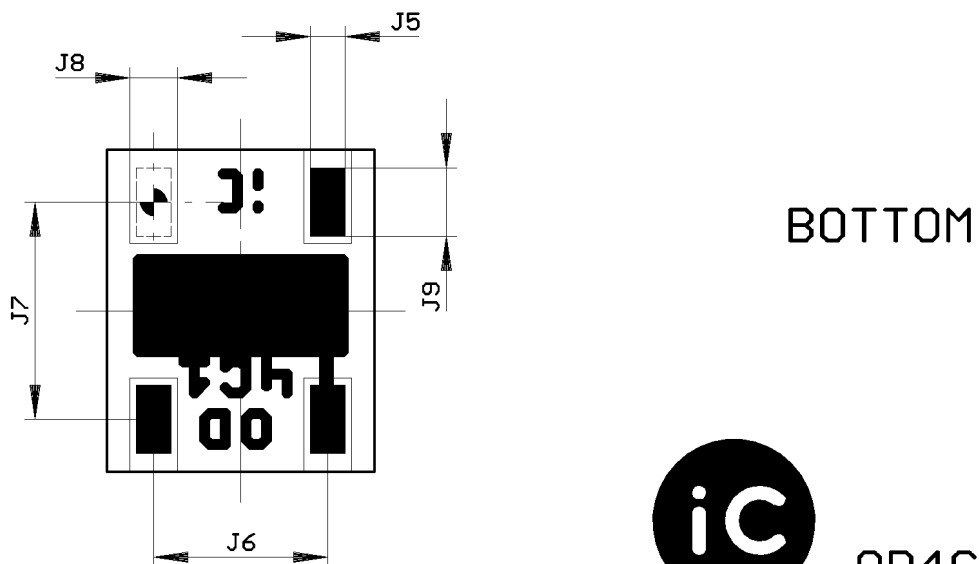
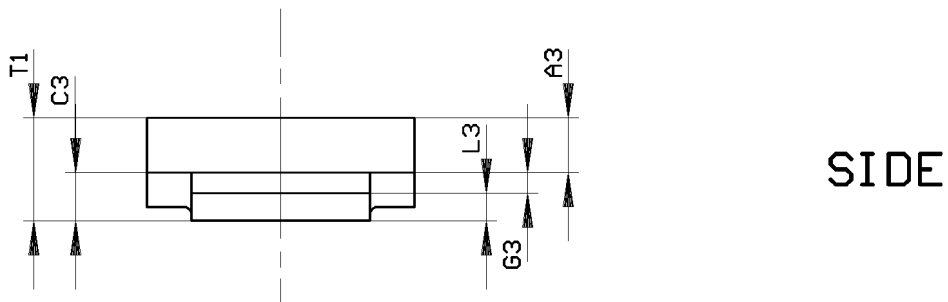
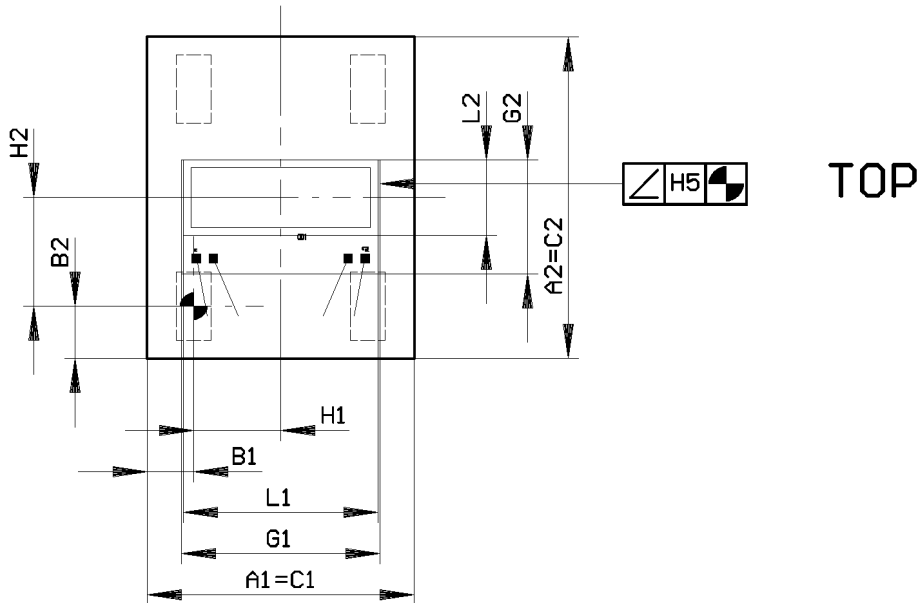
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PHYSICAL DIMENSIONS



OD4C_DRC

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DIMENSION TABLE

Item	Parameter	Comments					Unit
			Min.	Typ.	Max.	Tolerance	
Substrate							
A1	Outline X			3.9		±0.1	mm
A2	Outline Y			4.7		±0.1	mm
A3	Substrate Thickness	bottom package to bottom die	0.783	0.87	0.957		mm
Reference							
B1	Outline vs. Reference X			0.68		±0.22	mm
B2	Outline vs. Reference Y			0.7625		±0.22	mm
Frame Size and Shape (or Encapsulation)							
C1	Frame Outline X	equivalent to A1					
C2	Frame Outline Y	equivalent to A2					
C3	Frame Thickness		0.645	0.7	0.755		mm
Chip Placement							
G1	Chip Size X				2.9	-0.075	mm
G2	Chip Size Y				1.66	-0.075	mm
G3	Chip Thickness			0.3		±0.025	mm
H1	Chip Position vs. Reference X	center of sensor		1.27		±0.195	mm
H2	Chip Position vs. Reference Y	center of sensor		1.5875		±0.195	mm
H5	Chip Tilt Angle vs. Paddle					±1.6	DEG
Bottom Metal Pattern							
J5	Lead Size X			0.5		±0.03	mm
J6	Lead Pitch X (or Lead-Lead Distance X)			2.54			mm
J7	Lead Pitch Y (or Lead-Lead Distance Y)			3.175			mm
J8	Solder Stop Off			0.7		±0.1	mm
J9	Lead Size Y			1.0		±0.03	mm
Encapsulant (Glass Cover)							
L1	Glass Size X			2.85		±0.05	mm
L2	Glass Size Y			1.1		±0.05	mm
L3	Glass Thickness			0.4		±0.03	mm
Thickness Specifications							
T1	Overall Thickness		1.428		1.712		mm

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REVISION HISTORY

Rev	Notes	Pages affected
A0	Initial version	all
B0	New package model name, all tolerance specifications revised	all
C1	HDI Technology, RoHS compliance	all
D1	Convection reflow soldering peak temperature reduced to 245 °C	1, 4

GENERAL HANDLING INSTRUCTIONS

After opening the dry pack, devices must be mounted within 8 hours (in factory conditions of maximum 30 °C/60% RH) or must be stored at < 10% RH. Devices require baking before mounting if the Humidity

Indicator Card shows > 10% when read at 23 °C ±5 °C or if the conditions mentioned above are not met. Devices may be baked for 72 hours at 100 °C using high-temperature device containers (trays).

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